Introduction to MicroTCA





Courtesy CorEdge Networks

PICMG Specification Series

AMC Market Segments ATCA Carriers Proprietary Carriers MicroTCA

Courtesy Ericsson

When the technology market collapsed in 2001 it left the telecomm market with a lot of dark fiber and without the capital to light it up. The solution was standardized hardware platforms produced in much higher volumes and commensurately lower cost.



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MicroTCA Guiding Concepts

- Low Cost /High Volume
 - \$500 for Cube Common Components without redundancy 50K pcs in 2007
- Overhead to Payload ratio
 - Cost & Component Volume
- Broad Range of Applications /Configurability
 - Necessary to achieve extremely high volumes
- Markets
 - Telecom Edge Applications and Customer Premise Equipment
 - Medical
 - Enterprise & Data
 - Industrial
 - Digital Imaging



Courtesy Schroff/Pentair



Component Height

AMC Form Factors



4 The AMC ECN committee is planning to introduce the mid-size form factor

MicroTCA Form Factors







AMC I/O

+12 Volt Payload Power 3.3 Volt Management Power

Non-Redundant IPMI System Management

Clocks 1, 2 & 3 Bidirectional

Port 0 Gig-E Port 1 Gig-E or PCI-E use as redundant pairs in High Reliability uTCA Configurations

Port 2&3 SATA, SAS or FC

Port 4-7 Fat Pipes XAUI, PCI-E/AS or SRIO

Port 8-11 Fat Pipes XAUI, PCI-E/AS or SRIO use as redundant pairs in High Reliability uTCA Configurations

Port 12-20 Extended Options

PICINIC COMPUTERS

Each of the 21 Ports is capable 10 Gbps

MicroTCA Conceptual Elements

µ**TCA**[™]75mm Shelf

- Each Virtual Carrier Group
- Up to 12 AMC Modules
 10 Modules in Slots 3 to 12
- 1 or 2 MCH (pka VCM)
 - 1 in slot 2 (slot 13 filler panel)
- Power Module
- 0 to 2 Cooling Units
 One above



Courtesy of Ericsson & Rittal Kaparel



MCH MicroTCA Controller & Hub previously known as VCM (Virtual Carrier Manager)

- Fabric Switching for up to 60 Ports
 - 12 GbE minimum
 - 12 x 4 lanes XAUI, PCI-E or SRIO
- IPMI Management for 12 AMC modules
- Management for up to 4 Power Modules
- Management for up to 2 Cooling Units
- Optionally provides Shelf Management
- Front Panel Alarms
- Clock Distribution system
- Fabric Channel Uplink







Courtesy CorEdge Networks



Power Modules

- 300 to 600 Watts
- 16 Output Channels
 - 12 AMC Modules
 - 2 MCH (pka VCM)
 - 2 optional Cooling Units



MicroTCA Prototype Power Module 6/05

- N+1 Optional Redundancy
- Minimum 1 per Virtual Carrier up to 4 maximum
- Maximum load per Virtual Carrier 1120 Watts
- Custom ICs for output channel current limiting, hot swap control and power good underway



Single & Multiple Virtual Carriers Shelves

- 1 to 16 Carriers per Shelf
- Each VC has it's own power and MCH (pka VCM)
- Interconnected via up link fabric channels, which contain management traffic
- Clocks may also be interconnected between VCs



High Availability

- .999 to .99999
- Optional from none to fully redundant
 - Power & System Management use tri-stated connection for resources that are in the standby condition
 - Fabric can be redundant but require AMCs that are designed for this type of service
 - Clocks 1 & 3 are radial, 2 is radial and if redundant terminated at both ends at the MCHs
- Shelves can be designed with replaceable VC assemblies (sometimes referred to as Hot Swappable Cubes)



MicroTCA Topologies



MicroTCA Prototype for Bus & Board 1/06 Connectivity Diagram



Current Status & Timeline

- 1 Vendor is currently showing and selling prototype MCH (pka VCM) at least two other vendors have prototypes in development
- 2 Companies have prototypes in development
- Two companies prototype 75 & 150 mm shelves and Cubes
- A functional system running a wireless application was demonstrated at SuperComm 6/05 shown at right

•Several more prototypes shown at 3 GSM 3/06



Courtesy Ericsson



14 Specification approval by the executive committee is scheduled for end of May

About the Author



- Michael Franco is the President & CEO of Signal Stream Technologies, LLC a consulting services company.
- Chairman of the PICMG MicroTCA Subcommittee and former draft editor of the PICMG.AMC specification. Other standards work includes authorship of the mechanical, power and thermal sections of the AMC spec and chairman of the AMC Connector Workgroup and Vita 39 Subcommittee.

